



NO:RD-HH-SDH1174A  
Date:2010/03/25-R (REV:A4)

# 10/100 BASE-TX DUAL PORT MAGNETICS MODULES

## MODEL NO.: HH-022

### FEATURES:

RoHS Compliant

RoHS peak solder rating 260°C / 3~5 sec

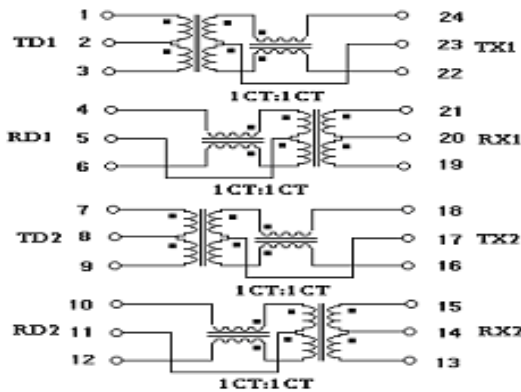
DESIGNED TO MEET IR REQUIREMENT

Operating temp. : -40°C TO +85°C

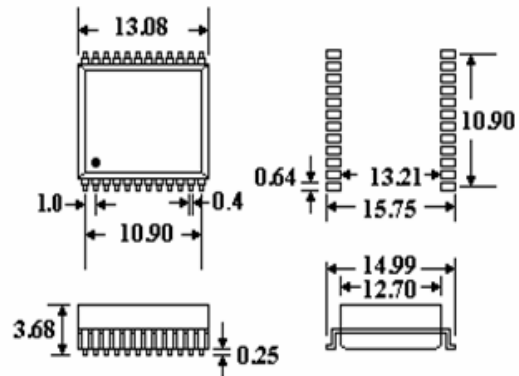
SPECIFICATIONS: AT 25°C

Part Number	Turns Ratio (±3%)	OCL uH, 8mA (MIN)	Insertion Loss (dB TYP)	Cross Talk (dB TYP)				Return Loss (dB MIN)				Common Mode Rejection (dB TYP)		HIPOT (VAC)
				1	30	60	100MHz	2~30	40	50	60~80MHz	1-60	60-200 MHz	
HH-022	TX/RX	350	1~100MHz	1	30	60	100MHz	2~30	40	50	60~80MHz	1-60	60-200 MHz	1500
	1CT:1CT		-1.2	-60	-45	-40	-35	-18	-16	-14	-12	-45	-35	

### SCHEMATICS:

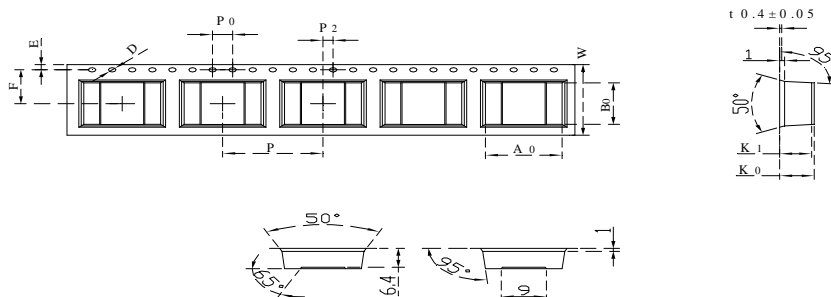


### DIMENSION: mm TOLERANCE: ±0.25



### Packing :

ITEM	W	A 0	B 0	K 0	K 1	P	E	F	D	D 1	P 0	P 2
D IM	24	$15.3^{+0.1}_{-0.2}$	$14.1^{+0.1}_{-0.1}$	$6.9^{+0.1}_{-0.1}$	$6.4^{+0.1}_{-0.1}$	$2.0^{+0.1}_{-0.1}$	$1.75^{+0.1}_{-0.1}$	$1.5^{+0.1}_{-0.1}$	$1.5^{+0.1}_{-0.0}$	$0.0^{+0.25}_{-0.0}$	$4.0^{+0.1}_{-0.1}$	$2.0^{+0.1}_{-0.1}$





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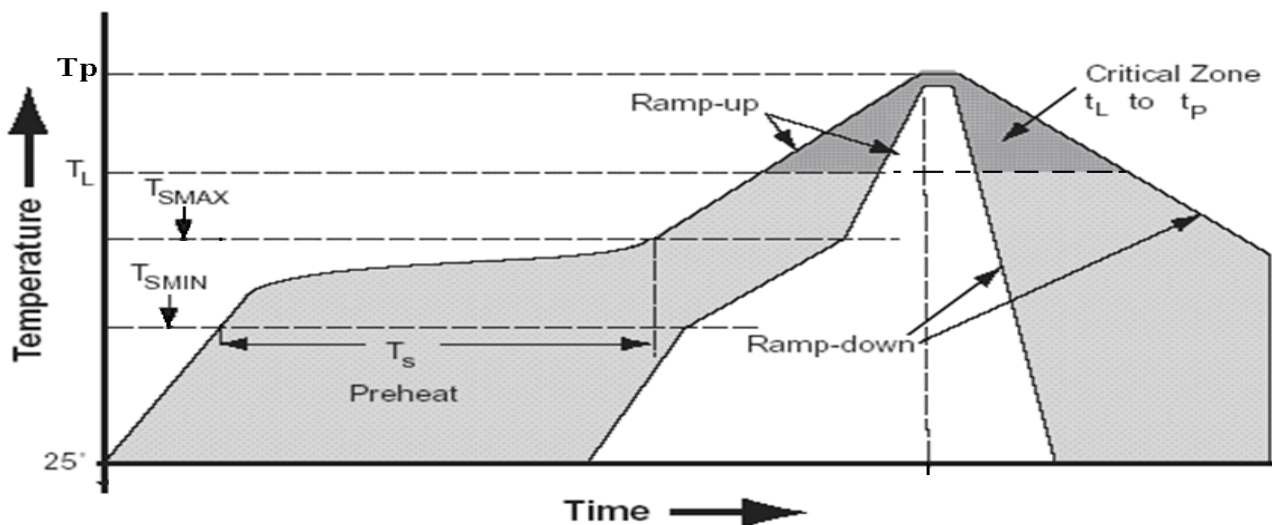
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Solder Reflow profile for Lead-Free packages.  
Package Peak Reflow Temperatures

### Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate( $T_L$ to $T_P$ )	3°C / Second Max.	
Preheat Temperature Min.( $T_s$ min.) Temperature Max.( $T_s$ max.) Time (min to max) ( $T_s$ )	150 °C 200 °C 60-180 sec	
$T_s$ max. to $T_L$ Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature ( $T_L$ ) Time ( $t_L$ )	217 °C 60-150 sec	
Peak Tempature ( $T_p$ ) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutees Max.	

### Profile



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### PACKING

1. Tape & Reel : 400pcs / Reel , 2000pcs / Carton
2. Dry Pack : 1pcs  
Product Description:(5g Silica Gel Desiccant)  
PH: 4-8  
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vocumm
4. Seal Per Jedec

